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WIRING SUBSTRATE USED FOR RESIN MOLDING AND PROCESS OF MANUFACTURING SEMICONDUCTOR DEVICE USING THE WIRING SUBSTRATE

ABSTRACT OF THE DISCLOSURE

An insulating substrate has a plurality of semiconductor chip mounting sections arranged one by one along a predetermined direction extending from one to the other end of the substrate, and a resin transmitting port. The resin transmitting port is located at a position in the vicinity of the one end along the predetermined direction and other than the semiconductor chip mounting section arranged nearest to the one end. A semiconductor chip is mounted on a respective semiconductor chip mounting section. A mold defines a cavity, including first and second cavity sections on the respective surfaces of the substrate, in such a manner that the first and second cavities communicates with each other by means of the resin transmitting port. A sealing resin is injected into the cavity, so that the resin flows through the resin transmitting port to fill both of the first and second cavity sections with the sealing resin.

Figure 1

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